

United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/865,006	05/23/2001	Krishna Parat	042390P7462D	4672
7590 04/19/2005			EXAMINER	
Michael A. Bernadicou			DIAZ, JOSE R	
BLAKELY, SO	OKOLOFF, TAYLOR &	& ZAFMAN LLP		
Seventh Floor		ART UNIT	PAPER NUMBER	
12400 Wilshire Boulevard			2815	
Los Angeles, (CA 90025-1026			_

DATE MAILED: 04/19/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

				<u>57</u> v		
	A	pplication No.	Applicant(s)			
Office Action Summary		09/865,006	PARAT ET AL.			
		xaminer	Art Unit			
		osé R. Díaz	2815			
The MAILING DATE of this Period for Reply	communication appeal	rs on the cover sheet w	vith the correspondence add	ress		
A SHORTENED STATUTORY PE THE MAILING DATE OF THIS CO - Extensions of time may be available under the after SIX (6) MONTHS from the mailing date of - If the period for reply specified above is less the - If NO period for reply is specified above, the note of the period for reply is specified above, the note of the period for reply is specified above, the note of the period for reply within the set or extended period period for the period for the period for the period for reply within the set or extended period for the period f	OMMUNICATION. provisions of 37 CFR 1.136(a of this communication. nan thirty (30) days, a reply with naximum statutory period will a od for reply will, by statute, cau ee months after the mailing dat). In no event, however, may a hin the statutory minimum of th pply and will expire SIX (6) MC use the application to become	n repty be timely filed hirty (30) days will be considered timely. DNTHS from the mailing date of this com ABANDONED (35 U.S.C. § 133).	nmunication.		
Status						
1) Responsive to communicati	on(s) filed on 24 Janu	ary 2005.				
2a) This action is FINAL.	• •	tion is non-final.				
•	Since this application is in condition for allowance except for formal matters, prosecution as to the ments is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims	io praedice anaer 2x p		5. 11, 700 0.0. 210.			
4) ⊠ Claim(s) <u>4 and 9-11</u> is/are p 4a) Of the above claim(s) 5) □ Claim(s) is/are allowe 6) ⊠ Claim(s) <u>4 and 9-11</u> is/are r 7) □ Claim(s) is/are object 8) □ Claim(s) are subject	is/are withdrawn ed. ejected. ted to.	from consideration.				
Application Papers						
9)☐ The specification is objected	to by the Examiner.			·		
10) ☐ The drawing(s) filed on is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.						
,, , ,	Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).					
Replacement drawing sheet(s) 11) The oath or declaration is ob	_	•				
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a) All b) Some * c) No 1. Certified copies of the 2. Certified copies of the 3. Copies of the certified application from the li	one of: priority documents he priority documents he priority documents he copies of the priority nternational Bureau (F	ave been received. ave been received in documents have bee PCT Rule 17.2(a)).	Application No n received in this National S	Stage		
Attachment(s)						
 Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing 	Pavious (PTO 049)		y Summary (PTO-413) o(s)/Mail Date			
Notice of Draftsperson's Patent Drawing Information Disclosure Statement(s) (PT Paper No(s)/Mail Date			Informal Patent Application (PTO-	152)		

Application/Control Number: 09/865,006

Art Unit: 2815

DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States
- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 2. Claim 4 is rejected under 35 U.S.C. 102(e) as being anticipated by Inoue (US Pat. No. 6,284,624 B1).

Regarding claim 4, Inoue teaches a method comprising:

forming a trench (4) in a silicon substrate (1) (see fig. 2);

growing an oxide (6) in said trench (see fig. 13);

removing all of said grown oxide (6) from said trench (see fig. 14);

growing a second oxide (23) in said trench (see fig. 15);

filling said trench with a dielectric (8) (see fig. 16);

growing a tunnel oxide (10) on said silicon substrate adjacent to said dielectric filled trench (see fig. 17);

forming a first polysilicon layer (26) on said tunnel oxide (see fig. 25);

forming an intepoly dielectric (27) on said first polysilicon layer (see fig. 25);

forming a polysilicon control gate (28) on said interpoly dielectric (see fig. 25).

Page 2

Application/Control Number: 09/865,006

Art Unit: 2815

Claims 9-11 are rejected under 35 U.S.C. 102(b) as being anticipated by Teng et al. (US Pat. No. 4,890,144).

Regarding claim 4, Teng et al. teaches a method comprising:

forming a trench (18) in a semiconductor substrate (12) between a first cell and a second cell (please consider the portions of the substrate that have isolation regions 16, which are located at the right and left sides of trench (18). See fig. 4);

forming an opening in a first dielectric material (20) in the trench (please note that layer 20 was removed to exposed the bottom surface of the trench. See fig. 5 and col. 4, lined 40-41);

forming a second dielectric material (24) in the opening in the fist dielectric material (see fig. 5)

forming a shared source region (30) through the opening between the first cell and the second cell (see fig. 5);

forming sidewall spacers with the second dielectric material (24) (please note that layer 24 is patterned in figure 6 to expose the bottom surface of the trench, so that layer 24 remains only on the sidewalls of the trench).

Regarding claim 10, Teng et al. further teaches growing a thermal oxide (32) in the trench (see fig. 6).

Regarding claim 11, Teng et al. further teaches forming the second dielectric material (24) with a chemical vapor deposition (CVD) process (see col. 4, lines 40-44).

Allowable Subject Matter

3. The indicated allowability of claims 9-11 is withdrawn in view of the newly discovered reference to Teng et al. Rejections based on the newly cited reference follow.

Response to Arguments

4. Applicant's arguments with respect to claims 4 and 9-11 have been considered but are most in view of the new grounds of rejection.

Correspondence

Any inquiry concerning this communication or earlier communications from the examiner should be directed to José R. Díaz whose telephone number is (571) 272-1727. The examiner can normally be reached on Monday through Thursday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on (571) 272-1664. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Application/Control Number: 09/865,006

Art Unit: 2815

Page 5

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

JRD 4/14/05

> TOM THOMAS SUPERVISORY PATENT EXAMINER